TECHNICAL DATA SHEET

SN60/PB40 SOLDER ALLOY

FEATURES
- Liquidus 190°C (374°F)
- High Purity
- Complies with IPC J-STD-006

DESCRIPTION
Sn60/Pb40 is composed of 60% tin, and 40% lead. This high purity alloy is suitable for electronic applications with a melting point of 183°C-190°C (361°F-374°F). Typical applications include soldering and plating, where Sn60/Pb40 is used as a coating for corrosion protection, and as a base for subsequent soldering operations.
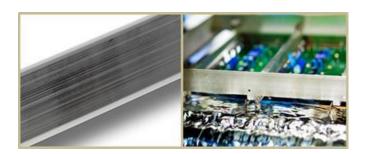
AVAILABILITY
Sn60/Pb40 is available in 1.1 kg (2.5 lb) triangular bars, hanging AIM Safety Bar and Solid Wire. Sn60/Pb40 is also available in AIM flux cored wire solders and solder pastes.

TYPICAL ALLOY COMPOSITION

Typical Alloy Composition	
Sn: 60.0	Pb: 40.0

TYPICAL MELTING TEMPERATURE

Typical Melting Temperature	
Solidus: 183°C (361°F)	Liquidus: 190°C (374°F)

HANDLING & STORAGE

Parameter	Time	Temperature
Shelf Life	Indefinite	Room Temperature

Indefinite shelf life applies to solid solder. For other product categories, refer to those specific TDSs. Consult AIM Sn60/Pb40 Safety Data Sheet for additional handling procedures and precautions.

FLUX COMPATIBILITY
Sn60/Pb40 bar solder is compatible with all major brands of no clean, RMA and water soluble electronic grade fluxes.

CLEANING
Refer to data sheets provided by the flux manufacturer.

SAFETY
Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

WWW.AIMSOLDER.COM   INFO@AIMSOLDER.COM